

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	30	V
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Forward Current @ T _T = +121°C	I _{F(AV)}	2.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	33	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	1.67	W
Power Dissipation (Note 7)	P _D	556	mW
Thermal Resistance Junction to Ambient (Note 6)	Reja	60	°C/W
Thermal Resistance Junction to Ambient (Note 7)	R _{0JA}	180	°C/W
Thermal Resistance Junction to Soldering (Note 8)	Rejs	10	°C/W
Operating Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T _{STG}	-40 to +150	°C

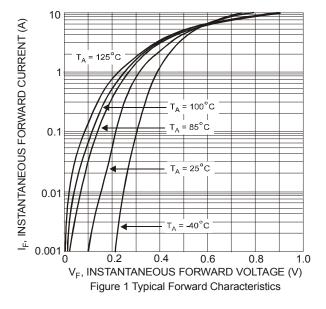
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

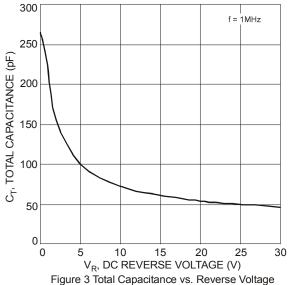
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 9)	V _{(BR)R}	30	_	_	V	I _R = 1.0mA
Forward Voltage	V _F	_	0.310 0.375	0.42	V	I _F = 1.0A I _F = 2.0A
Leakage Current (Note 9)	I _R	_	0.260	 1.0	mA	V _R = 5V, T _A = +25°C V _R = 30V, T _A = +25°C
Total Capacitance	Ст	_	76	_	pF	V _R = 10V, f = 1.0MHz

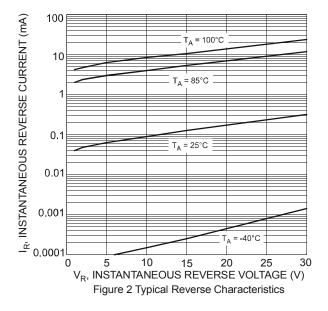
Notes:

- 6. Part mounted on 2"x2" GETEK board with 1"x1" copper pad, 25% anode, 75% cathode. T_A = +25°C.
 7. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com.
 8. Theoretical R_{OJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 9. Short duration pulse test used to minimize self-heating effect.









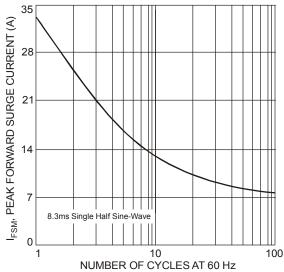
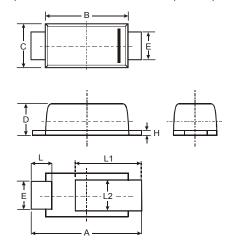


Figure 4 Maximum Non-Repetitive Peak Forward Surge Current



Package Outline Dimensions

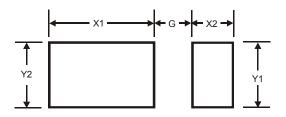
 $Please\ see\ AP02002\ at\ http://www.diodes.com/datasheets/ap02002.pdf\ for\ latest\ version.$



PowerDI [®] 123				
Dim	Min	Max	Тур	
Α	3.50	3.90	3.70	
В	2.60	3.00	2.80	
O	1.63	1.93	1.78	
D	0.93	1.00	0.98	
Е	0.85	1.25	1.00	
Н	0.15	0.25	0.20	
L	0.55	0.75	0.65	
L1	1.80	2.20	2.00	
L2	0.95	1.25	1.10	
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4



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